WHAT IS CLAIMED IS:

1. A surface acoustic wave filter in which a plurality of pairs of comb electrode patterns are formed on an upper surface of a chip substrate made of a piezoelectric material, comprising a high-resistance pattern formed to surround a peripheral portion of the chip substrate on an upper surface side thereof, and a plurality of patterns formed to connect the high-resistance pattern to the respective comb electrode patterns.

2. A surface acoustic wave filter in which a plurality of pairs of comb electrode patterns are formed on an upper surface of a chip substrate made of a piezoelectric material, comprising a first pattern formed on the upper surface of the chip substrate so as to extend from part of at least one member of each of the pairs of comb electrode patterns, a second pattern formed on the upper surface of the chip substrate so as to oppose the first pattern at a predetermined gap, and a dummy electrode pattern formed on the upper surface of the chip substrate so as to be adjacent to the second pattern and connected thereto.

3. A surface acoustic wave filter in which a plurality of pairs of comb electrode patterns are formed on an upper surface of a chip substrate made of a piezoelectric material,

piezoelectric material, wherein opposing portions of two comb electrode patterns that form a pair are not sharp.

4. A surface acoustic wave filter apparatus in which the surface acoustic wave filter according to claim 1 is accommodated in a package.

5. A surface acoustic wave filter apparatus in which the surface acoustic wave filter according to claim 2 is accommodated in a package.

6. A surface acoustic wave filter apparatus in which the surface acoustic wave filter according to claim 3 is accommodated in a package.

7. An apparatus according to claim 4, wherein the package is a plastic package.

8. An apparatus according to claim 5, wherein the package is a plastic package.

9. An apparatus according to claim 6, wherein the package is a plastic package.

10. An apparatus according to claim 7, wherein a metal plate-like portion is formed at a center of the package.

11. An apparatus according to claim 8, wherein a metal plate-like portion is formed at a center of the package.

12. An apparatus according to claim 9, wherein a metal plate-like portion is formed at a center of the

package.

13. An apparatus according to claim 10, wherein a lower surface of the chip substrate which constitutes the surface acoustic wave filter is fixed to the package with a conductive adhesive.

14. An apparatus according to claim 11, wherein a lower surface of the chip substrate which constitutes the surface acoustic wave filter is fixed to the package with a conductive adhesive.

15. An apparatus according to claim 12, wherein a lower surface of the chip substrate which constitutes the surface acoustic wave filter is fixed to the package with a conductive adhesive.